

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning at page 2, line 26, with the following rewritten paragraph:

However, in the method in which a heater is provided outside the exhaust pipe, a part of the heat energy is radiated toward the outside of the exhaust pipe, so that the energy efficiency for heating the inner wall face of the exhaust pipe to be contacted by an exhaust gas or the like to a predetermined temperature is poor, and results in an increase in power consumption.

Please replace the paragraph beginning at page 4, line 3, with the following rewritten paragraph:

Disclosure Summary of the Invention

The present invention has been made in view of the above-described circumstances, and it is an object of the present invention to minimize adhesion of by-products to the inner wall face of the duct or processing chamber, etc., exposed to a processing gas or the like in a semiconductor manufacturing device or the like, thereby providing a semiconductor manufacturing device and a heating unit thereof which improve the yield of wafers to be processed, increase the operating time, and reduce power consumption by improving the energy efficiency.

Please replace the paragraph beginning at page 17, line 4, with the following rewritten paragraph:

Best Mode for Carrying Out Detailed Description of the Invention

Hereinafter, ~~best modes~~embodiments of the present invention are described with reference to the accompanying drawings.

Please replace the paragraph beginning at page 19, line 3, with the following rewritten paragraph:

The heating main body 51 is formed of thin and cylindrical inner shell 51a and outer shell 51b as a pair of metal plates, a thin plate-shaped resistive heating element 51c sandwiched and

covered between ~~the~~ both shells 51a and 51b, a spacer 51d that joins the edges of ~~the~~ both shells 51a and 51b and seals up the resistive heating element 51c, and so on.

Please replace the paragraph beginning at page 19, line 9, with the following rewritten paragraph:

The spacer 51d is provided at the edges (edges of the lower end opening 50b, the rectangular opening 50c, and the circular opening 50d) in regions to be exposed to a processing gas in the edges of ~~the~~ both shells 51a and 51b to completely prevent the resistive heating element 51c from being exposed to the processing gas or the like.

Please replace the paragraph beginning at page 19, line 15, with the following rewritten paragraph:

The attaching portion 52 is formed of a flange 52a joined to the inner shell 51a and a flange 52b joined to the outer shell 51b, and between ~~the~~ both flanges 52a and 52b, a conducting lead 51c' connected to the resistive heating element 51c and a lead 51c'' of a thermocouple as a temperature sensor for measuring the temperature of the resistive heating element 51c are sandwiched and drawn to the connector 53. Namely, the flanges 52a and 52b are not completely sealed up but are opened to the outside. At the connector 53, a power supply cable 90 is connected to the lead 51c', and a cable 91 to be connected to a measuring instrument is connected to the lead 51c''.

Please replace the paragraph beginning at page 31, line 15, with the following rewritten paragraph:

The clamp mechanism 300 includes, as shown in Fig. 14 through Fig. 16, a plurality of clamp blocks 301 having grooves 301a with roughly V-shaped sections for receiving the flange portions 412 and 412 and the flange portions 412 and 422 so as to press these closer to each other, a plurality (herein, four) of first link plates 302 that join ~~one~~ first side portions 301b of the clamp blocks 301 to each other, a plurality (herein, four) of second link plates 303 that join ~~the~~ second side portions 301c of the clamp blocks 301 to each other, and a bolt 304 as a

fastening member rotatably supported on one clamp block 301 and a female screw that is formed on the other clamp block 301 and is screwed to the bolt 304.